

FEATURES:

- Typical $t_{sk(o)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- $V_{cc} = 3.3V \pm 0.3V$, Normal Range
- $V_{cc} = 2.7V$ to $3.6V$, Extended Range
- CMOS power levels (0.4 μ W typ. static)
- All inputs, outputs, and I/O are 5V tolerant
- Supports hot insertion
- Available in SSOP package

DRIVE FEATURES:

- High Output Drivers: $\pm 24mA$
- Reduced system switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

DESCRIPTION:

The LVCH16601A 18-bit universal bus transceiver is built using advanced dual metal CMOS technology. The LVCH16601A combines D-type latches and D-type flip-flops to allow data flow in transparent, latched and clocked modes.

Data flow in each direction is controlled by output-enable (\overline{OEAB} and \overline{OEBA}), latched-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (\overline{CKENAB} and \overline{CKENBA}) inputs.

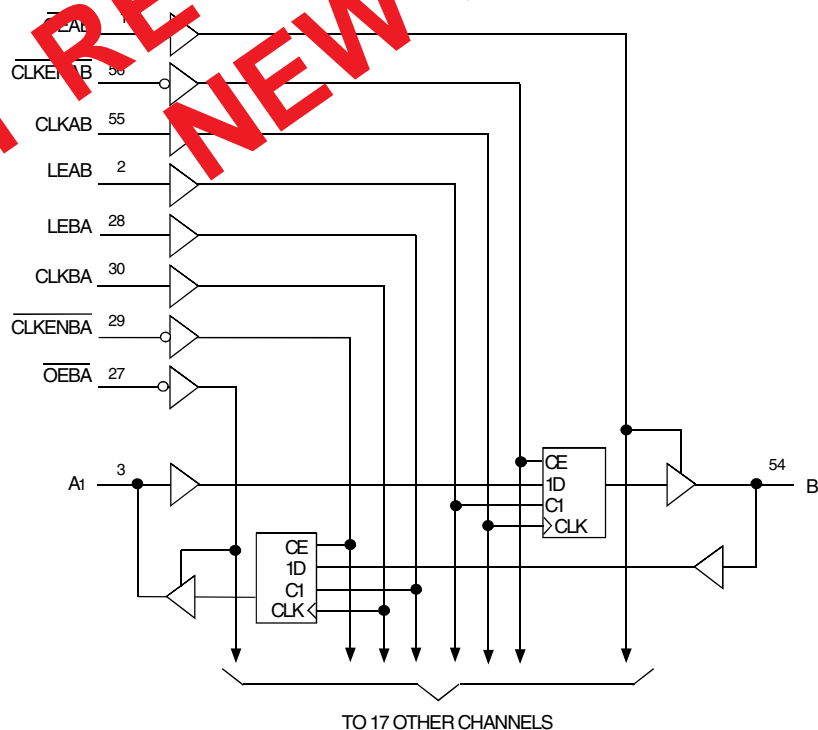
For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-to-B data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output enable \overline{OEAB} is active low. When \overline{OEAB} is low, the outputs are active. When \overline{OEAB} is high, the outputs are in the high impedance state. Data flow for B to A is similar to that of A to B but uses \overline{LEBA} , LEBA, CLKBA and \overline{CKENBA} .

All pins can be driven from either 3.3V or 5V devices. This feature allows the use of this device as a translator in a mixed 3.3V/5V supply system.

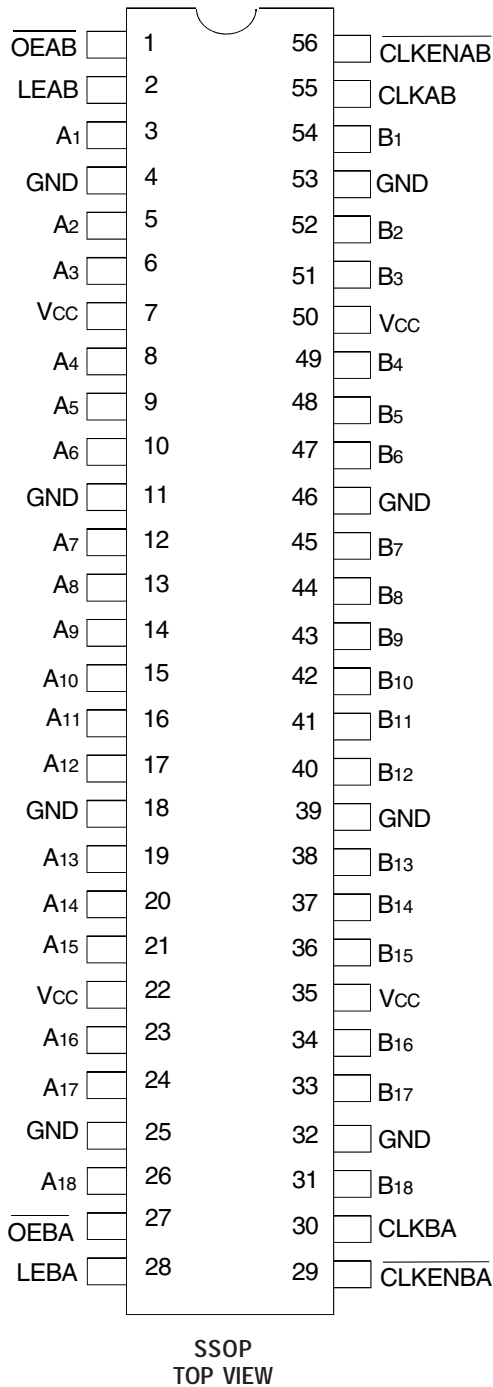
The LVCH16601A has been designed with a $\pm 24mA$ output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

The LVCH16601A has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +6.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-50 to +50	mA
I _{IK} I _{OK}	Continuous Clamp Current, V _I < 0 or V _O < 0	-50	mA
I _{CC} I _{SS}	Continuous Current through each V _{CC} or GND	±100	mA

NOTE:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

PIN DESCRIPTION

Pin Names	Description
\overline{OEAB}	A-to-B Output Enable Input (Active LOW)
\overline{OEBA}	B-to-A Output Enable Input (Active LOW)
LEAB	A-to-B Latch Enable Input
LEBA	B-to-A Latch Enable Input
CLKAB	A-to-B Clock Input
CLKBA	B-to-A Clock Input
A _x	A-to-B Data Inputs or B-to-A 3-State Outputs ⁽¹⁾
B _x	B-to-A Data Inputs or A-to-B 3-State Outputs ⁽¹⁾
$\overline{CLKENAB}$	A-to-B Clock Enable Input (Active LOW)
$\overline{CLKENBA}$	B-to-A Clock Enable Input (Active LOW)

NOTE:

1. These pins have "Bus-Hold". All other pins are standard inputs, outputs, or I/Os.

FUNCTION TABLE^(1,2)

Inputs					Outputs
$\overline{CLKENAB}$	\overline{OEAB}	LEAB	CLKAB	A _x	B _x
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B ⁽³⁾
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B ⁽³⁾
L	L	L	H	X	B ⁽⁴⁾

NOTES:

- H = HIGH Voltage Level
X = Don't Care
L = LOW Voltage Level
Z = High-Impedance
↑ = LOW-to-HIGH transition
- A-to-B data flow is shown. B-to-A data flow is similar but uses \overline{OEBA} , LEBA, CLKBA, and $\overline{CLKENBA}$.
- Output level before the indicated steady-state input conditions were established.
- Output level before the indicated steady-state input conditions were established, provided that CLKAB was HIGH before LEAB went LOW.

CAPACITANCE (T_A = +25°C, F = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	4.5	6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	6.5	8	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	6.5	8	pF

NOTE:

1. As applicable to the device type.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

 Operating Condition: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
V _{IH}	Input HIGH Voltage Level	V _{CC} = 2.3V to 2.7V		1.7	—	—	V
		V _{CC} = 2.7V to 3.6V		2	—	—	
V _{IL}	Input LOW Voltage Level	V _{CC} = 2.3V to 2.7V		—	—	0.7	V
		V _{CC} = 2.7V to 3.6V		—	—	0.8	
I _{IH} I _{IL}	Input Leakage Current	V _{CC} = 3.6V	V _I = 0 to 5.5V	—	—	±5	μA
I _{OZH} I _{OZL}	High Impedance Output Current (3-State Output pins)	V _{CC} = 3.6V	V _O = 0 to 5.5V	—	—	±10	μA
I _{OFF}	Input/Output Power Off Leakage	V _{CC} = 0V, V _{IN} or V _O ≤ 5.5V		—	—	±50	μA
V _{IK}	Clamp Diode Voltage	V _{CC} = 2.3V, I _{IN} = -18mA		—	-0.7	-1.2	V
V _H	Input Hysteresis	V _{CC} = 3.3V		—	100	—	mV
I _{CC1} I _{CC2} I _{CC3}	Quiescent Power Supply Current	V _{CC} = 3.6V	V _{IN} = GND or V _{CC}	—	—	10	μA
			$3.6 \leq V_{IN} \leq 5.5V^{(2)}$	—	—	10	
ΔI _{CC}	Quiescent Power Supply Current Variation	One input at V _{CC} - 0.6V, other inputs at V _{CC} or GND		—	—	500	μA

NOTES:

- Typical values are at V_{CC} = 3.3V, +25°C ambient.
- This applies in the disabled state only.

BUS-HOLD CHARACTERISTICS

Symbol	Parameter ⁽¹⁾	Test Conditions		Min.	Typ. ⁽²⁾	Max.	Unit
I _{BHH} I _{BHL}	Bus-Hold Input Sustain Current	V _{CC} = 3V	V _I = 2V	-75	—	—	μA
			V _I = 0.8V	75	—	—	
I _{BHH} I _{BHL}	Bus-Hold Input Sustain Current	V _{CC} = 2.3V	V _I = 1.7V	—	—	—	μA
			V _I = 0.7V	—	—	—	
I _{BHHO} I _{BHLO}	Bus-Hold Input Overdrive Current	V _{CC} = 3.6V	V _I = 0 to 3.6V	—	—	±500	μA

NOTES:

- Pins with Bus-Hold are identified in the pin description.
- Typical values are at V_{CC} = 3.3V, +25°C ambient.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	VCC = 2.3V to 3.6V	IOH = - 0.1mA	VCC - 0.2	—	V
		VCC = 2.3V	IOH = - 6mA	2	—	
		VCC = 2.3V	IOH = - 12mA	1.7	—	
		VCC = 2.7V		2.2	—	
		VCC = 3V		2.4	—	
		VCC = 3V		IOH = - 24mA	2	
VOL	Output LOW Voltage	VCC = 2.3V to 3.6V	IOL = 0.1mA	—	0.2	V
		VCC = 2.3V	IOL = 6mA	—	0.4	
			IOL = 12mA	—	0.7	
		VCC = 2.7V	IOL = 12mA	—	0.4	
		VCC = 3V	IOL = 24mA	—	0.55	

NOTE:
 1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate VCC range. TA = - 40°C to + 85°C.

OPERATING CHARACTERISTICS, VCC = 3.3V ± 0.3V, TA = 25°C

Symbol	Parameter	Test Conditions	Typical	Unit
CPD	Power Dissipation Capacitance per Transceiver Outputs enabled	CL = 0pF, f = 10Mhz		pF
CPD	Power Dissipation Capacitance per Transceiver Outputs disabled			

SWITCHING CHARACTERISTICS⁽¹⁾

Symbol	Parameter	V _{CC} = 2.7V		V _{CC} = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	
t _{PLH} t _{PHL}	Propagation Delay Ax to Bx or Bx to Ax	—	5.4	—	4.6	ns
t _{PLH} t _{PHL}	Propagation Delay LEBA to Ax, LEAB to Bx	—	6.2	—	5.2	ns
t _{PLH} t _{PHL}	Propagation Delay CLKBA to Ax, CLKAB to Bx	—	6.3	—	5.3	ns
t _{PZH} t _{PZL}	Output Enable Time \overline{OEBA} to Ax, \overline{OEAB} to Bx	—	6.8	—	5.6	ns
t _{PHZ} t _{PLZ}	Output Disable Time \overline{OEBA} to Ax, \overline{OEAB} to Bx	—	6	—	5.2	ns
t _{SU}	Set-up Time HIGH or LOW Ax to CLKAB, Bx to CLKBA	1.5	—	1.5	—	ns
t _H	Hold Time HIGH or LOW Ax to CLKAB, Bx to CLKBA	0.8	—	0.8	—	ns
t _{SU}	Set-up Time HIGH or LOW Ax to LEAB, Bx to LEBA	Clock LOW	1	—	1	ns
		Clock HIGH	1	—	1	
t _{SU}	Set-up Time, $\overline{CLKENAB}$ to CLKAB	2.1	—	2.1	—	ns
t _{SU}	Set-up Time, $\overline{CLKENBA}$ to CLKBA	2.1	—	2.1	—	ns
t _H	Hold Time HIGH or LOW Ax after LEAB, Bx after LEBA	1.8	—	1.8	—	ns
t _H	Hold Time, $\overline{CLKENAB}$ after CLKAB	0.5	—	0.5	—	ns
t _H	Hold Time, $\overline{CLKENBA}$ after CLKBA	0.5	—	0.5	—	ns
t _w	LEAB or LEBA Pulse Width HIGH	3	—	3	—	ns
t _w	CLKAB or CLKBA Pulse Width HIGH or LOW	3	—	3	—	ns
t _{SK(O)}	Output Skew ⁽²⁾	—	—	—	500	ps

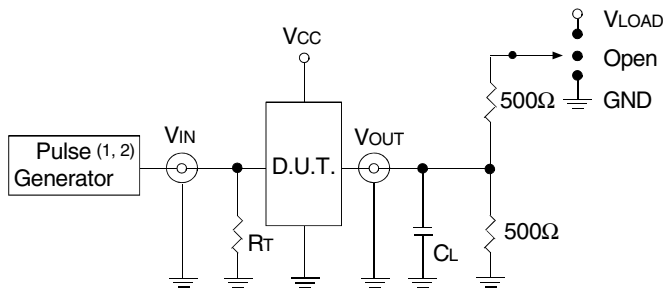
NOTES:

1. See TEST CIRCUITS AND WAVEFORMS. T_A = - 40°C to + 85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	V _{CC} ⁽¹⁾ =3.3V±0.3V	V _{CC} ⁽¹⁾ =2.7V	V _{CC} ⁽²⁾ =2.5V±0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF



LVC Link

Test Circuit for All Outputs

DEFINITIONS:

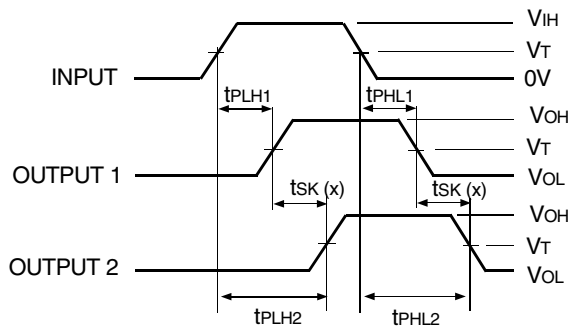
C_L = Load capacitance: includes jig and probe capacitance.
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_r ≤ 2.5ns; t_r ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_r ≤ 2ns; t_r ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other Tests	Open



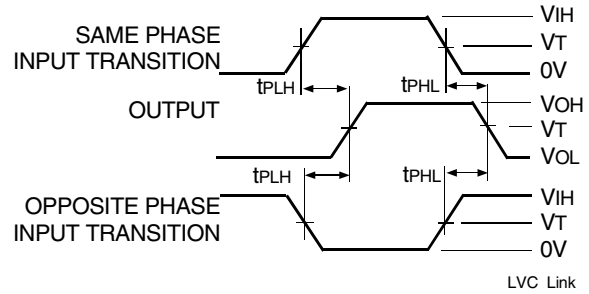
$$tsk(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

LVC Link

Output Skew - tsk(x)

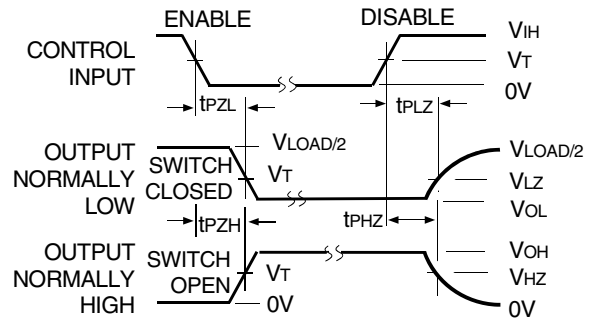
NOTES:

1. For tsk(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For tsk(b) OUTPUT1 and OUTPUT2 are in the same bank.



LVC Link

Propagation Delay

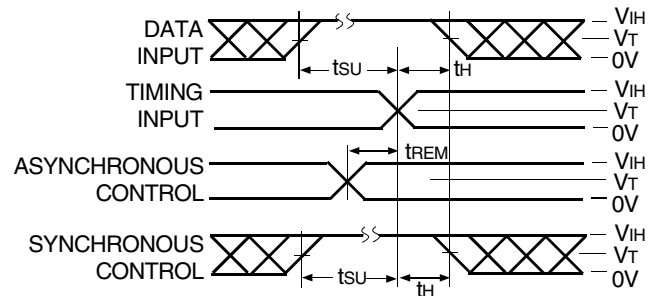


LVC Link

Enable and Disable Times

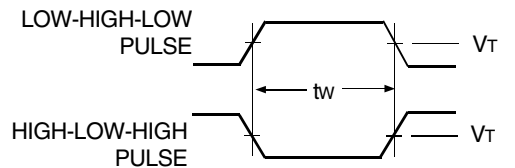
NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.



LVC Link

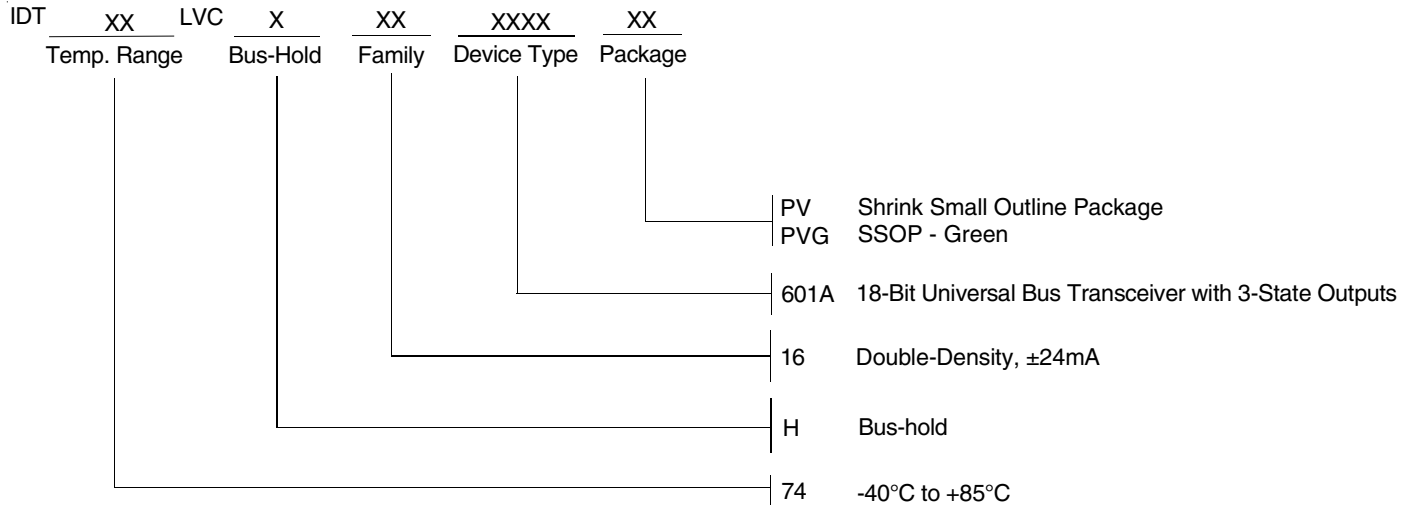
Set-up, Hold, and Release Times



LVC Link

Pulse Width

ORDERING INFORMATION



DATASHEET DOCUMENT HISTORY

10/28/2013 PDN# CQ-13-03 issued. See IDT.com for PDN specifics.
09/06/2019 Datasheet changed to Obsolete Status.

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(Rev.1.0 Mar 2020)

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